

Electrical And Mechanical Characteristics

	Standard	Type B and IDC Assemblies	Type Q (inversed)
Number of Pins		12, 26, 50, 68 and 80	12, 26, 50, 68 and 80
Technical data			
Climate Category	DIN EN 60068-1 test b	-55/125/56 IDC Assembly (depends on cable)	-55/125/56
Bearing and operating temperature area		-55/125 °C IDC Assembly (depends on cable)	-55/125 °C
Current rating	IEC60512 test 5b	By ambient temperature: 20°C 1,2 A 70°C 0,9 A 100°C 0,6 A IDC Assembly (depends on cable)	By ambient temperature: 20°C 1,2 A 70°C 0,9 A 100°C 0,6 A
Air – and creepage distance		0,4mm	0,4mm
Comparative figure of voltage	IEC 112	CTI-150	CTI-150
Voltage rating	DIN VDE 0110	Has to be determined according to client-specific using case (degree of environmental pollution) according to VDE 0110	Has to be determined according to client-specific using case (degree of environmental pollution) according to VDE 0110
Dielectric strength	IEC 60512	contact – contact 500V IDC Assembly (depends on cable)	contact – contact 500V
Contact resistance	IEC 60512 test 2a	< 25 mΩ	< 25 mΩ
Insulation resistance	IEC 60512 test 3a	> 10 ⁴ MΩ IDC Assembly (depends on cable)	> 10 ⁴ MΩ
Vibration	IEC 60512 test 6d	10 – 2000 Hz 20g	10 – 2000 Hz 20g
Contact disturbance (while vibration sine)	IEC 60512 test 2e	< 1 μs	< 1 μs
Shock halvesine	IEC 60512 test 6c	50g 11 ms	50g 11 ms
Contact disturbance (while shock halvesine)	IEC 60512 test 2e	< 1 μs	< 1 μs
Mechanical operation (mating cycles)	IEC 60512 test 9a	> 500 mating cycles	> 500 mating cycles
Insertion and withdrawal force	IEC 60512 test 13b	12 cont.: 6 N max. 26 cont.: 13 N max. 50 cont.: 26 N max. 68 cont.: 35 N max. 80 cont.: 40 N max.	12 cont.: 6 N max. 26 cont.: 13 N max. 50 cont.: 26 N max. 68 cont.: 35 N max. 80 cont.: 40 N max.
Gauge retention force	IEC 60512 test 16e	0,10 N min.	0,10 N min.

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Process-conditions			
Solder temperature max.	IEC 68-2-20		
Hand soldering temperature max.		3,5s at 350°C	3,5s at 350°C
Dip soldering temperature max.		10s at 260°C	10s at 260°C
SMT-Reflow soldering temperature max.		10s at 260°C	10s at 260°C
Warning		soldering of press-fit connectors not to be recommended	soldering of press-fit connectors not to be recommended
Coplanarity		< 0,1mm	< 0,1mm
IDC (Insulation Displacement Connection)		0/55 °C	0/55 °C
Materials			
Housing: plastic material (symbol)		LCP	LCP
CTI value	IEC 112	CTI 150	CTI 150
UL flame rating		UL 94 V-0	UL 94 V-0
UL file		E 83005	E 83005
Contact and mating area			
Base material		Cu alloy	Cu alloy
Plating		Au over Ni	Au over Ni
Termination area			
Base material		Cu alloy	Cu alloy
Solder, press-fit and IDC-technology		Sn	Sn
Environment compatibility			
recycling		no flame-retardent additives, no toxic additives allow easy recycling	
Product-approval and customer specific tests			
UL		file E 84703	file E 84703
CSA		in preparation	in preparation